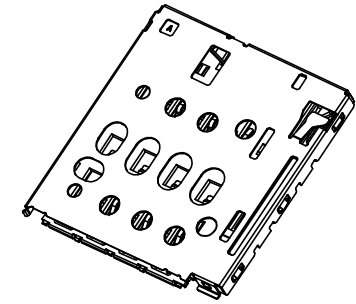
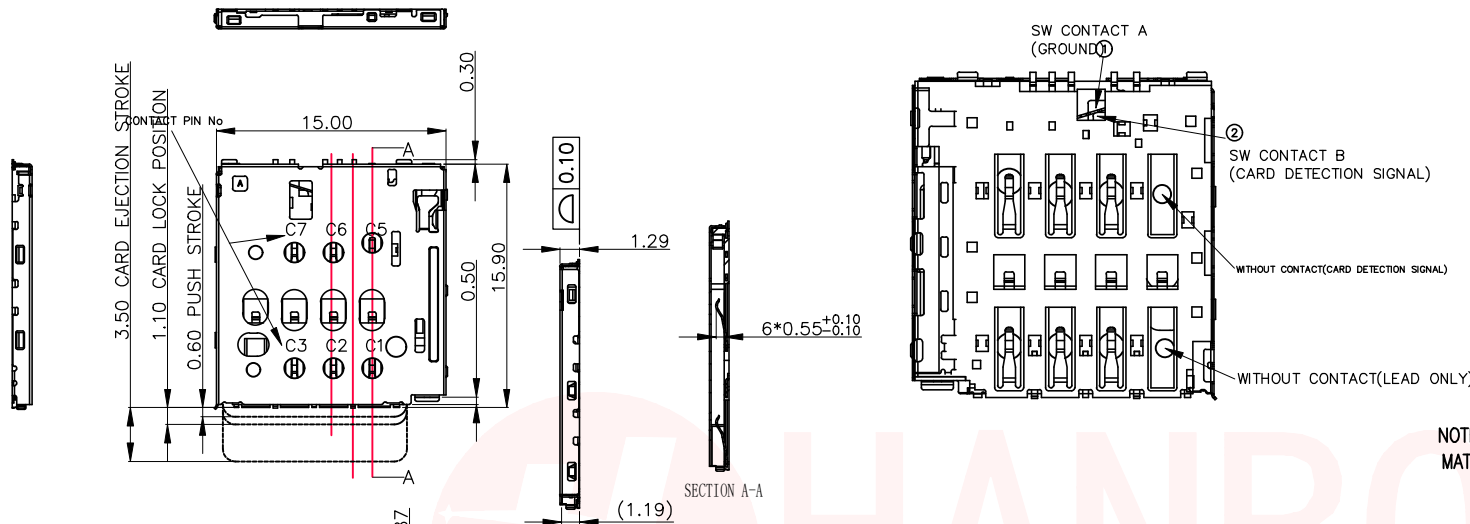
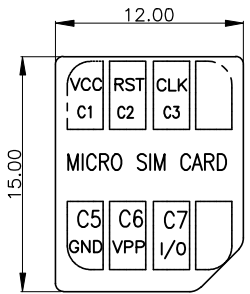
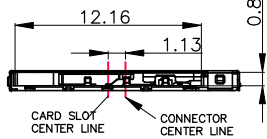




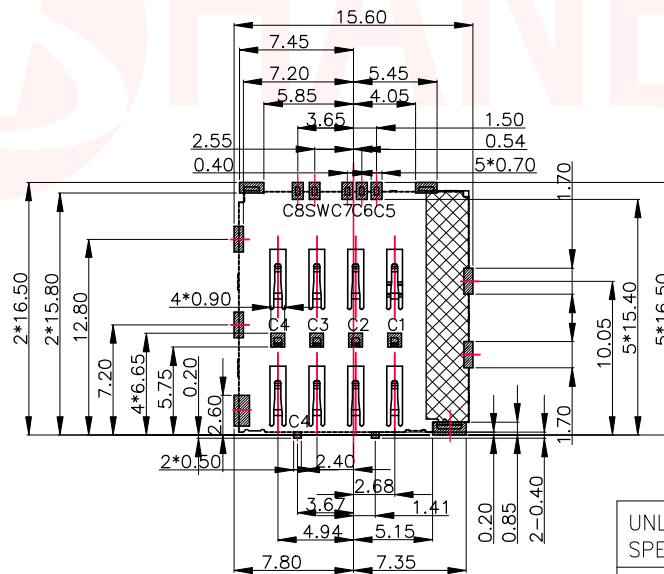
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



3D REFERENCE MODE(F)



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



NOTES:
MATERIAL:
Housing: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
Shell: SUS
PLATING:
Contact: Contact Area: Au 1u", Solder area: Gold Flash;
Shell: Plate 30u" Ni Over Au Min all over
Solder area: Gold
Electrical: Flash
Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:3,000 Insertions
Temperature: 260°C ±5"

MICRO SIM CARD

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

■ CIRCUIT TRACE KEEP OUT AREA
▨ SMT SOLDER AREA

CARD INSERTION	STATE	CARD DETECT SW
CARD UN-INSERTION	CLOSE	② SW CONTACT B (CARD DETECTION SIGNAL) ① SW CONTACT A (USE ONL)
CARD INSERTION	OPEN	② SW CONTACT B (CARD DETECTION SIGNAL) ① SW CONTACT A (USE ONL)

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	MICRO SIM PUSH PUSH 1.29H 卡座		
X :±0.30	X :±2°	DWN	xiong	PART NO. SMO-1030	
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:10F 1
CUSTOMER COPY					